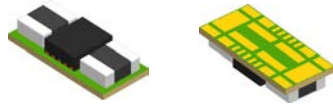


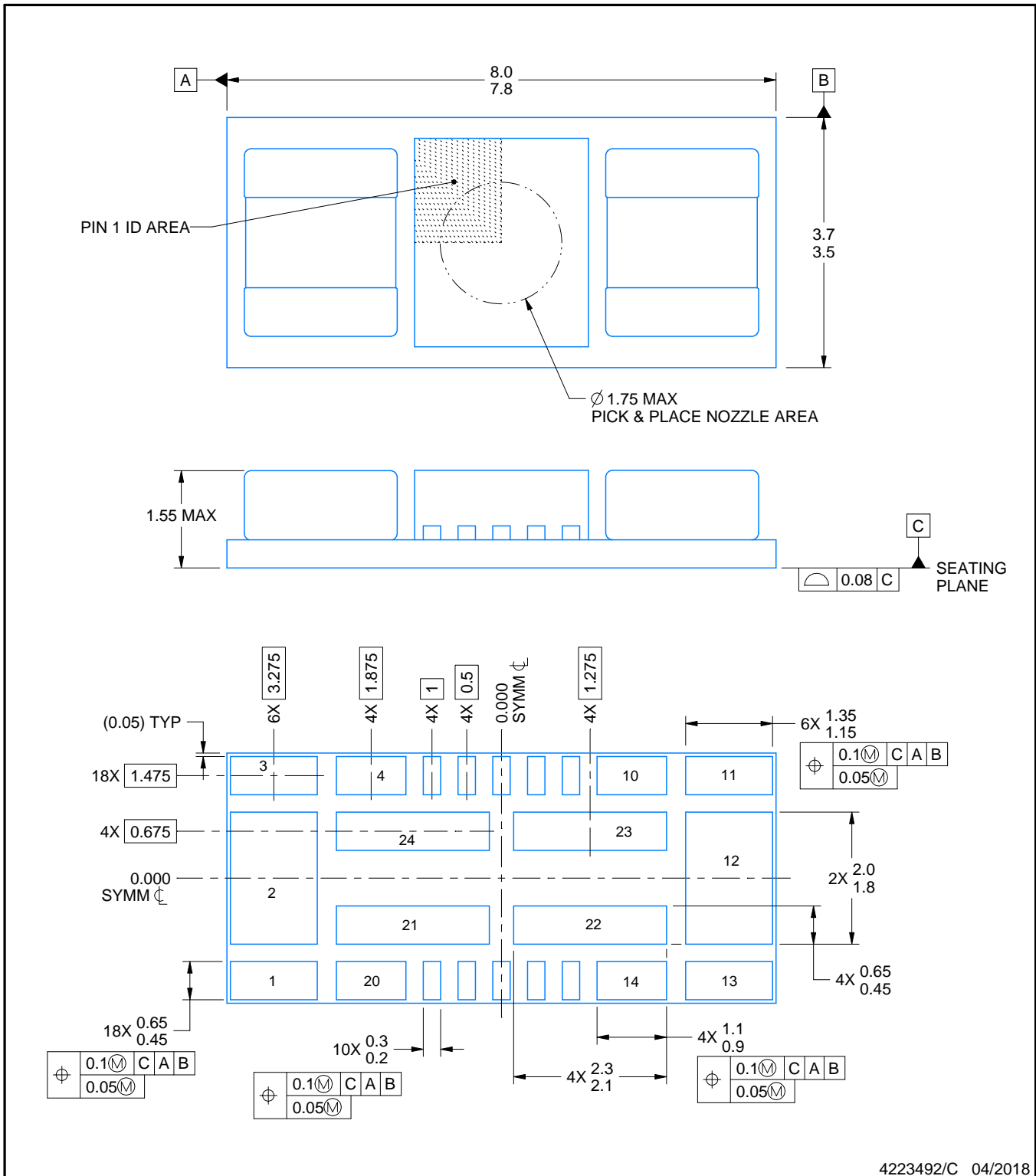
MOP0024A



PACKAGE OUTLINE

QFM - 1.55 mm max height

QUAD FLAT MODULE



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NOTES:

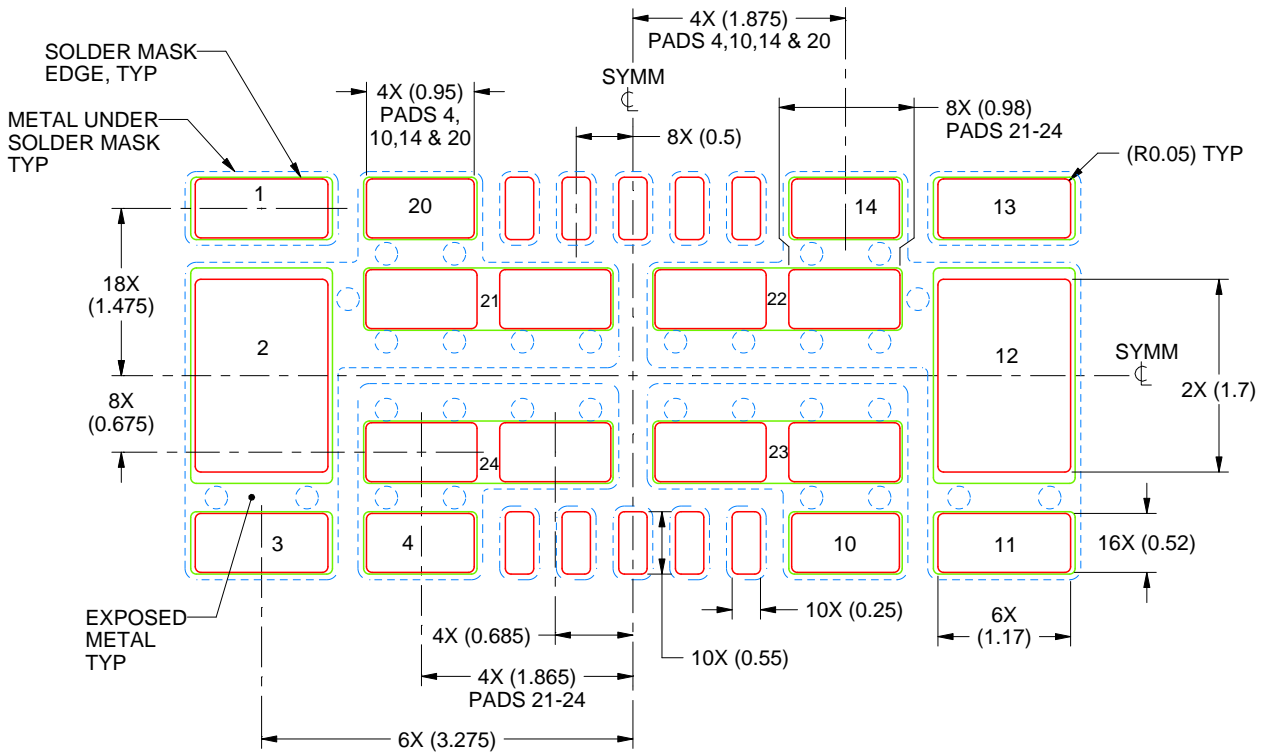
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE STENCIL DESIGN

MOP0024A

QFM - 1.55 mm max height

QUAD FLAT MODULE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

PADS 1, 3, 11 & 13: 88%

PADS 4, 10, 14 & 20: 90%

PADS 2, 12 & 21-24: 84%

SCALE:15X

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NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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